

PBX3216MC02 Specification

Operating Temp. : -40°C~+85°C

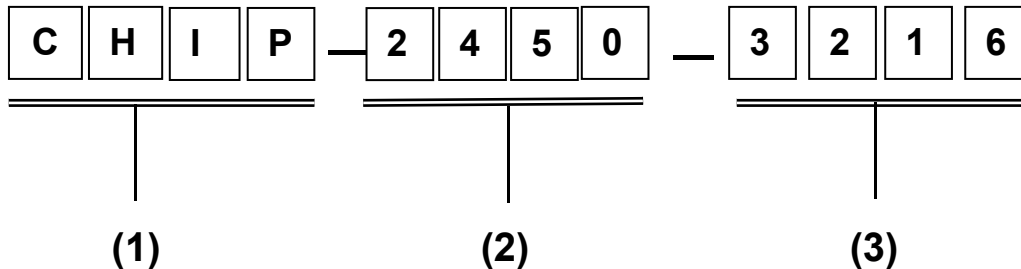
1. FEATURES:

- Light weight, compact
- Wide bandwidth, low cost
- Built-in antenna with high gain

2. APPLICATIONS:

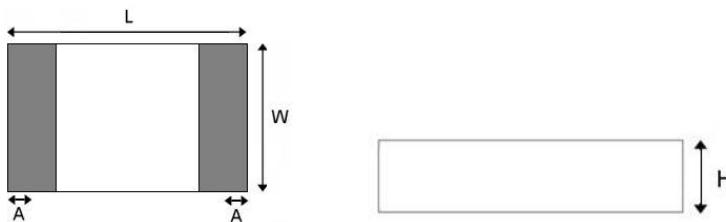
- Bluetooth, Wireless LAN, Mobile TV
- Home RF System, etc

3. PRODUCT IDENTIFICATION




- (1) Product type: Multilayer chip Antenna
 (2) Center Frequency: 2450MHz
 (3) External Dimensions (L×W) (mm): 3.2*1.6

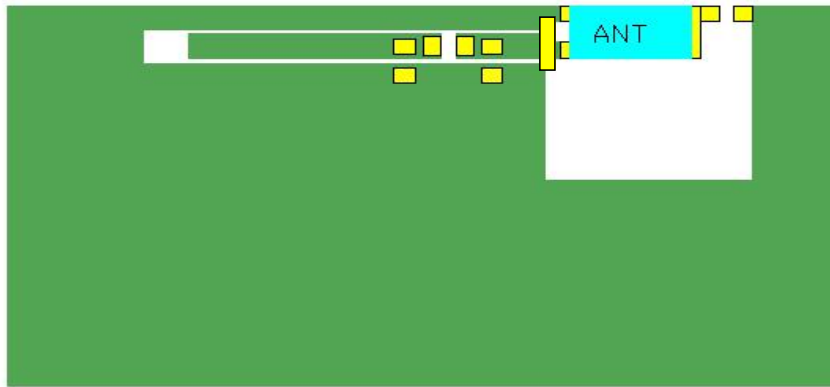
4. SHAPE AND DIMENSIONS:



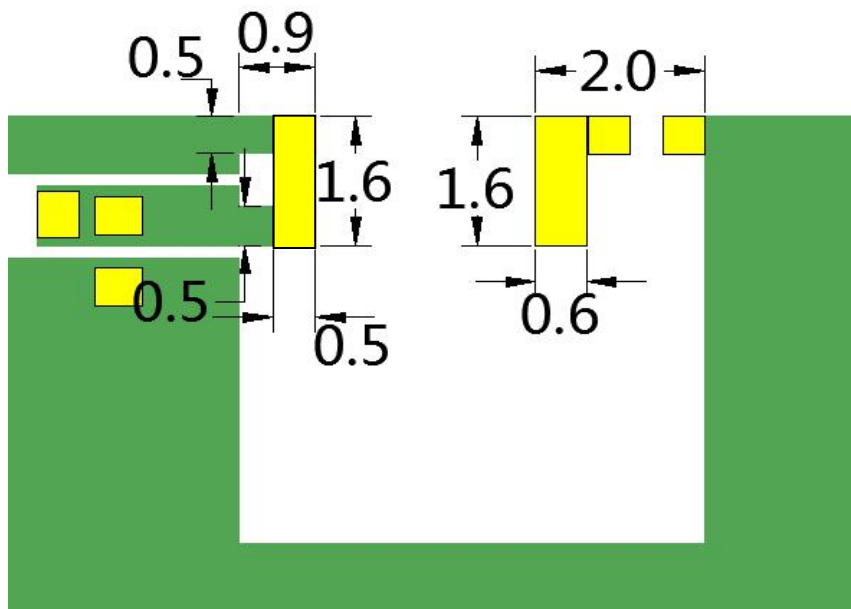
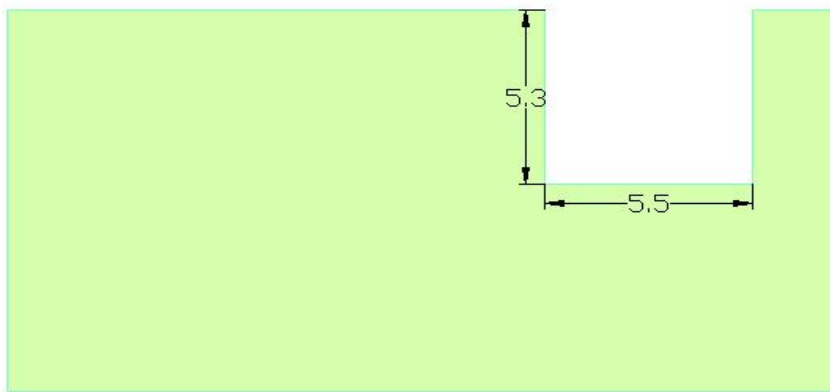
L	W	H	A
3.2±0.2	1.6±0.2	0.52±0.1	0.4±0.1


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DESIGNED BY: Sera	APPROVED BY: XD			
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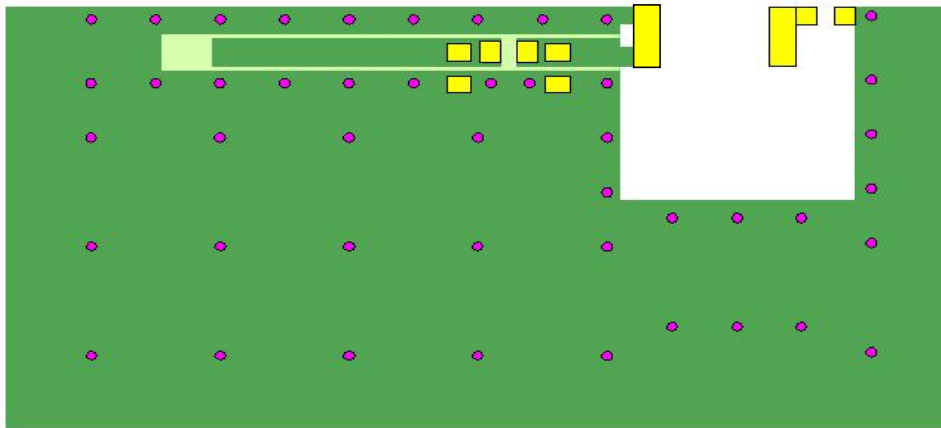
unit: mm



- Antenna
- PAD
- Bottom spread of copper
- Top spread of copper

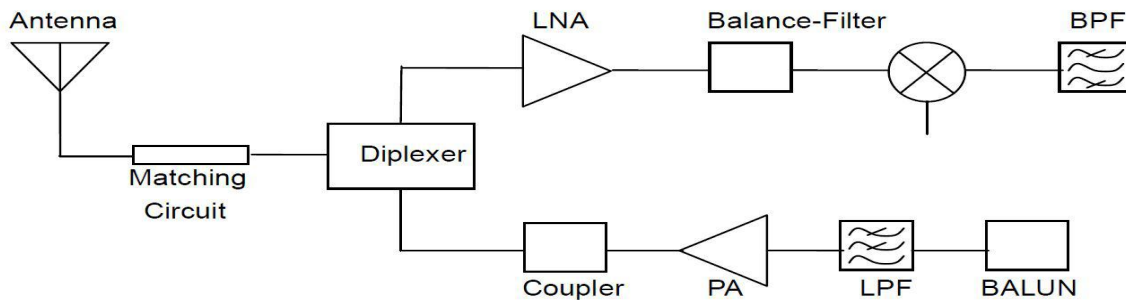


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- Antenna
- PAD
- Bottom spread of copper
- Top spread of copper
- Slotting

APPLICATION GUIDE



5. SPECIFICATIONS:

test item	specification
bandwidth	2400~2483MHz
polarization mode	linear polarization
* maximum gain	2.67dBi
* efficient	72.30%
input impedance	50Ω

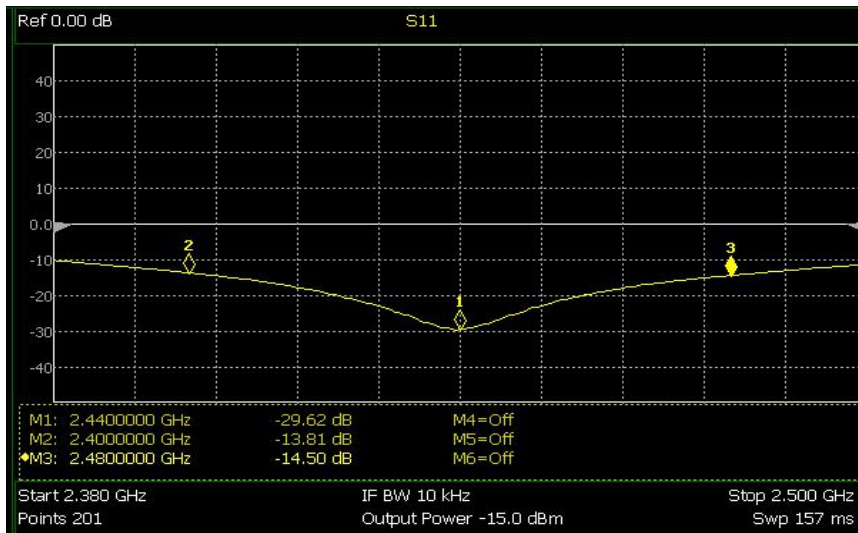
* Test condition: Test board size 90*40 mm

Matching circuit: Pi matching circuit will be required

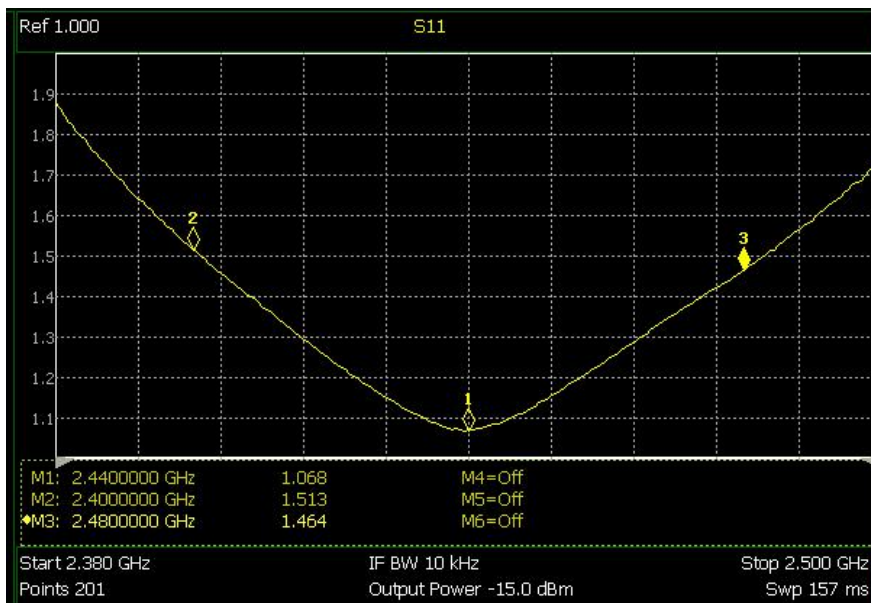
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6. Electrical Characteristics :

Return loss



Standing wave ratio



Mark	Frequency	VSWR
1	2400 MHz	1.513
2	2440 MHz	1.068
3	2480 MHz	1.464

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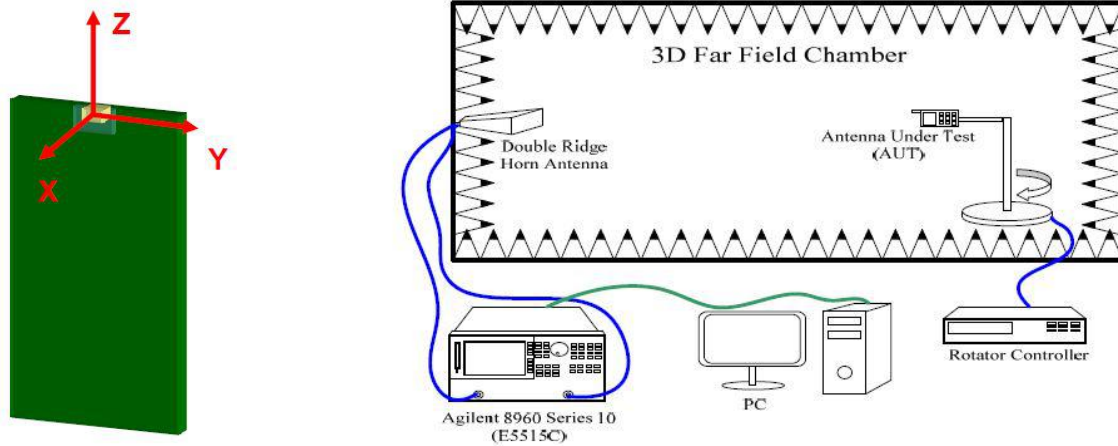
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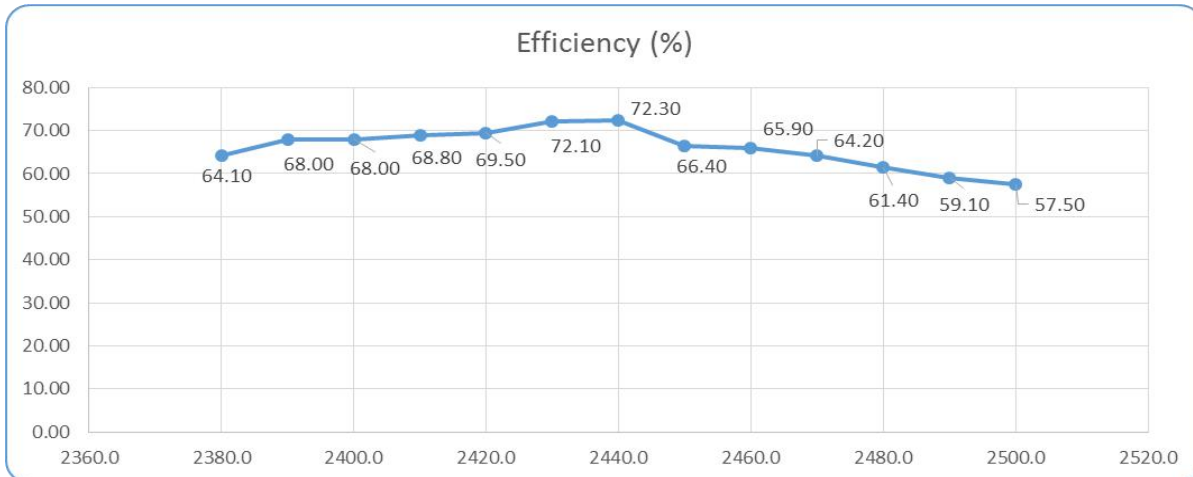
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Radiation Pattern

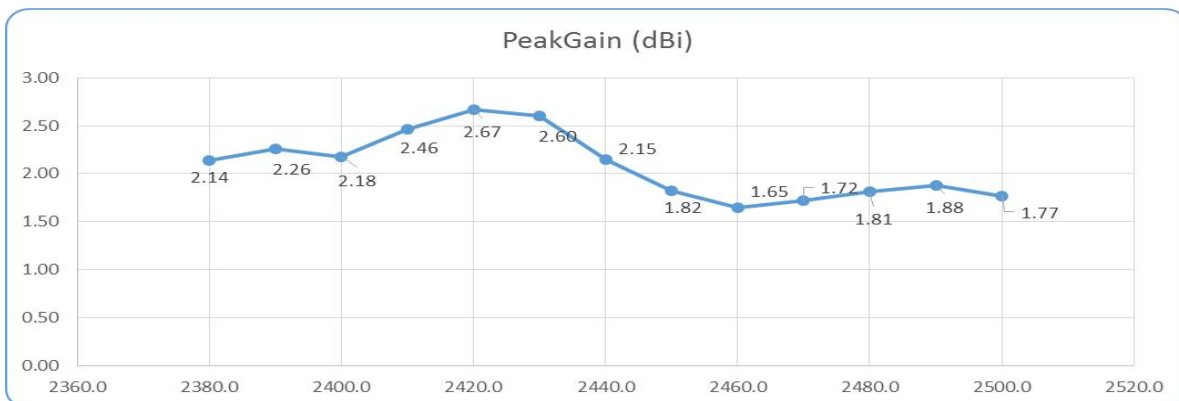
The Gain pattern is measured in FAR-field chamber. DUT is placed on the table of rotator, a standard horn antenna and Vector Network Analyzer is used to collect data.



© efficiency



maximum gain



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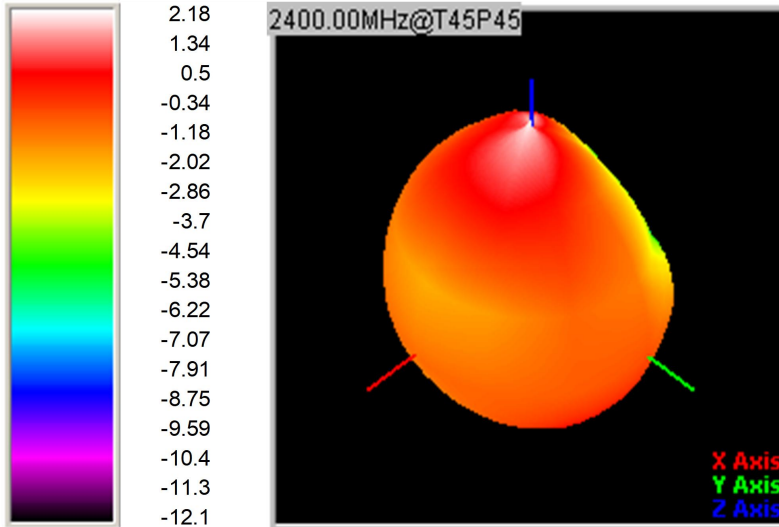
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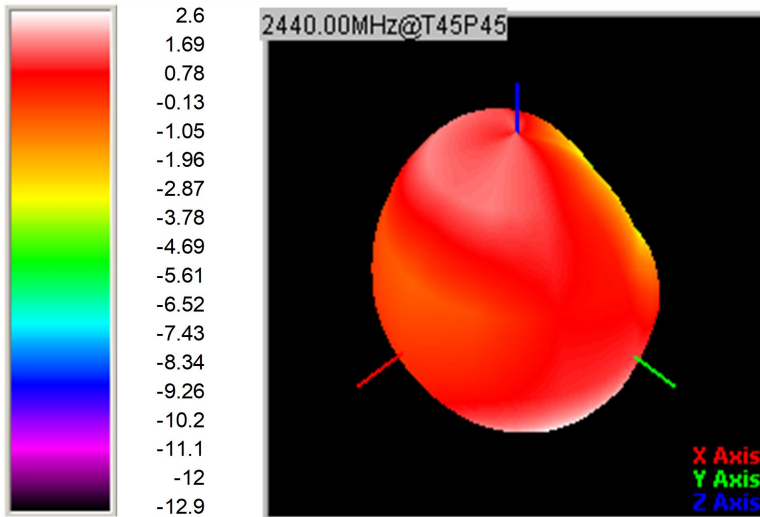
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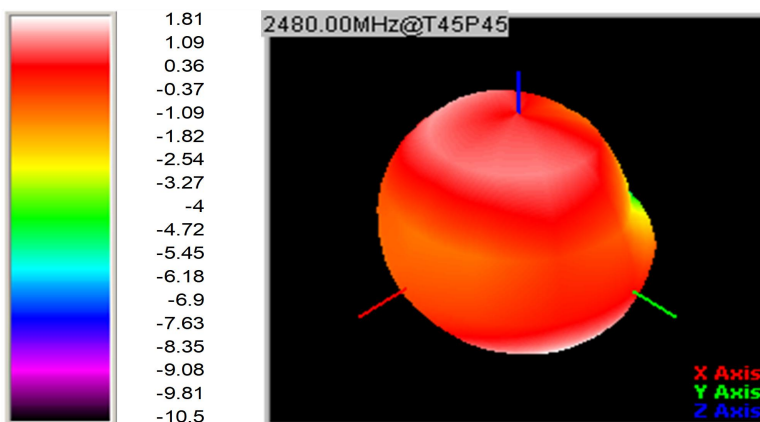
© 3D Gain Pattern (2400 MHz)



© 3D Gain Pattern (2440 MHz)



© 3D Gain Pattern (2480 MHz)



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7. Environmental Characteristics

(1) Reliability Test

Item	Condition	Specification
Thermal shock	<ol style="list-style-type: none"> 30±3 minutes at -40° C±5° C, Convert to +105° C (5 minutes) 30±3 minutes at +105° C±5° C, Convert to -40° C (5 minutes) Total 100 continuous cycles 	No apparent damage Fulfill the electrical spec. after test.
Humidity resistance	<ol style="list-style-type: none"> Humidity: 85% R.H. Temperature: 85±5° C Time: 1000 hours. 	No apparent damage Fulfill the electrical spec. after test.
High temperature resistance	<ol style="list-style-type: none"> Temperature: 150° C±5° C Time: 1000 hours. 	No apparent damage Fulfill the electrical spec. after test.
Low temperature resistance	<ol style="list-style-type: none"> Temperature: -40° C±5° C Time: 1000 hours. 	No apparent damage Fulfill the electrical spec. after test.
Soldering heat resistance	<ol style="list-style-type: none"> Solder bath temperature : 260±5°C Bathing time: 10±1 seconds 	No apparent damage
Solderability	The dipped surface of the terminal shall be at least 95% covered with solder after dipped in solder bath of 245±5°C for 3±1 seconds.	No apparent damage

(2) Storage Condition

(a) At warehouse:

The temperature should be within 0 ~ 30°C and humidity should be less than 60% RH.

The product should be used within 1 year from the time of delivery.

(b) On board:

The temperature should be within -40~85°C and humidity should be less than 85% RH.

(3) Operating Temperature Range

Operating temperature range : -40°C to +105°C.

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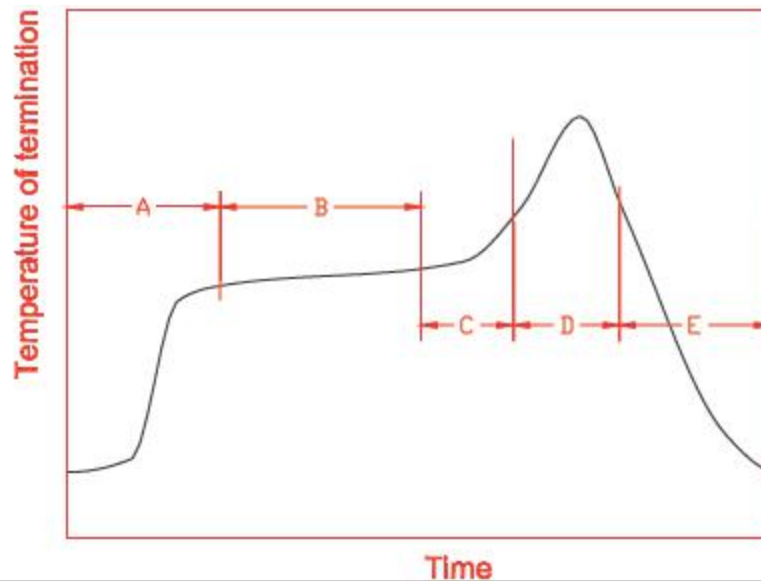
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8. Recommended Reflow Soldering



A	1 st rising temperature	The normal to Preheating temperature	30s to 60s
B	Preheating	140°C to 160°C	60s to 120s
C	2 nd rising temperature	Preheating to 200°C	20s to 40s
D	Main heating	if 220°C	50s~60s
		if 230°C	40s~50s
		if 240°C	30s~40s
		if 250°C	20s~40s
		if 260°C	20s~40s
E	Regular cooling	200°C to 100°C	1°C/s ~ 4°C/s

*reference: J-STD-020C


(1) Soldering Gun Procedure

Note the follows, in case of using solder gun for replacement.

- The tip temperature must be less than 350° C for the period within 3 seconds by using soldering gun under 30 W.
- The soldering gun tip shall not touch this product directly.

(2) Soldering Volume

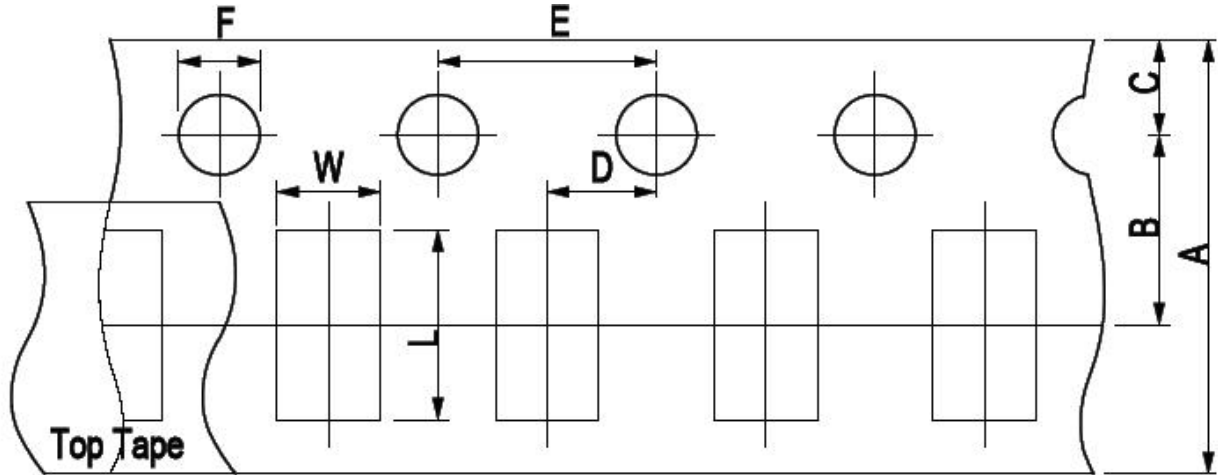
Note that excess of soldering volume will easily get crack the body of this product.

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9. Taping Package and Label Marking: (unit: mm)

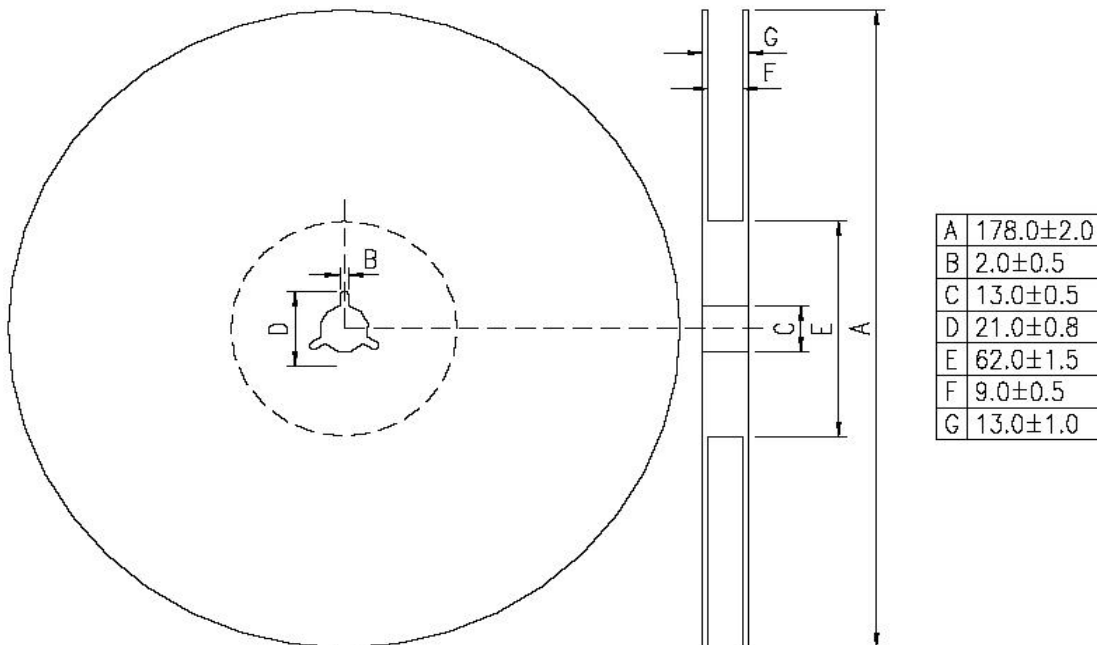
(1) Quantity/Reel: 5000pcs/Reel

(2) Carrier tape dimensions



Type	A	B	C	D	E	F	L	W
2450-21	8.00±0.3	3.50±0.05	1.75±0.1	2.00±0.05	4.00±0.1	1.50±0.1	2.30±0.1	1.55±0.1

(3) Taping reel dimensions



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